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Constraints

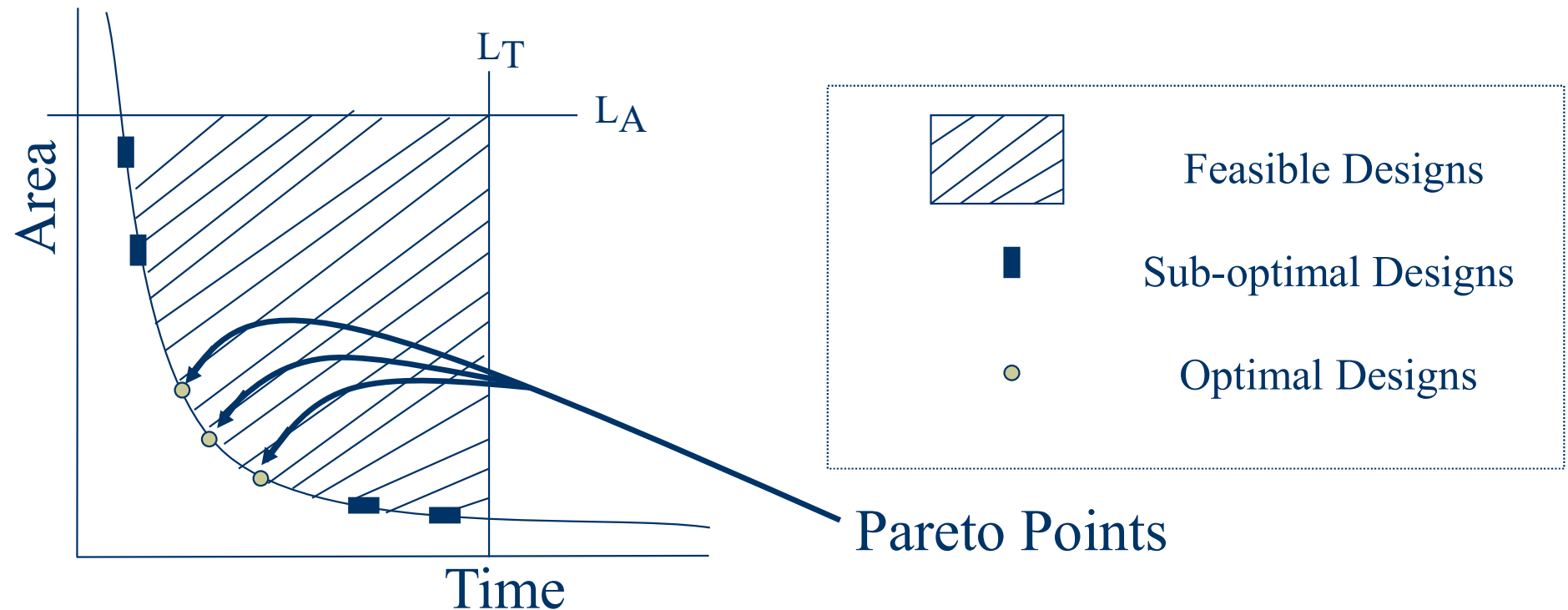
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Trade-Off



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- ◆ Synthesis comprises of developing some hardware to meet certain specifications
- ◆ But rarely are all specifications met
- ◆ “*You can meet some specifications all of the time, all specifications for some time, but never all specifications all the times*” – adapted from **Abraham Lincoln**



- ◆ Constraints are what ‘specifications’ are normally known as
- ◆ They specify the requirements or the expectations from a manufactured device
- ◆ Some constraints are technology dependent and exist by default while others are design dependent and decide by the engineer
- ◆ Constraints can be broadly categorized under two heads
 - Optimization
 - Design Rule

- ◆ The characteristics of a Chip depends highly on the environment in which it is working
- ◆ The environment restrictions exist on a design but the designer can choose an appropriate one from many
- ◆ The environment chosen decides the characteristics of the cells being used
- ◆ The three environment constraints are
 - Operating Condition
 - Wire Load Models
 - Wire Load Mode

Operating Condition



- ◆ The effect of PVT the operating conditions on a design has been already seen
- ◆ When a IC is being designed it should be ensured that the chip works for both the extremes of the permissible operating conditions
- ◆ The power, delay aspects of the design are checked at both the worst and best case conditions
- ◆ To ensure that both setup and hold are met both the best and worst operating conditions should be specified
- ◆ Operating Condition can be considered as the first and foremost constraint

Wire Load Models

- ◆ The delays due to interconnects can account upto 65% of the composite delay of the chip
- ◆ The appropriate wire load model chosen is a major factor in calculating wire delays
- ◆ Many a times designers use ‘zero wire delay’ model for rapid and easy calculations of net delays
 - Which is as good as ignoring the wire delays
- ◆ Wire load models are selected by default based on the area of the circuit being designed
- ◆ The ASIC designer can choose a optimistic or pessimistic wire load model from the many available in the libraries

Wire Load Modes

- ◆ The wire delays mainly depend on the wire load mode in consideration
- ◆ For hierarchal designs the wire load modes specify as to which wire load model is to be chosen for delay calculation
- ◆ Though there may exist a default wire load mode in the library the ASIC designer can again change the wire load mode from one of the below as per the analysis being carried out
 - Top
 - Segmented
 - Enclosed

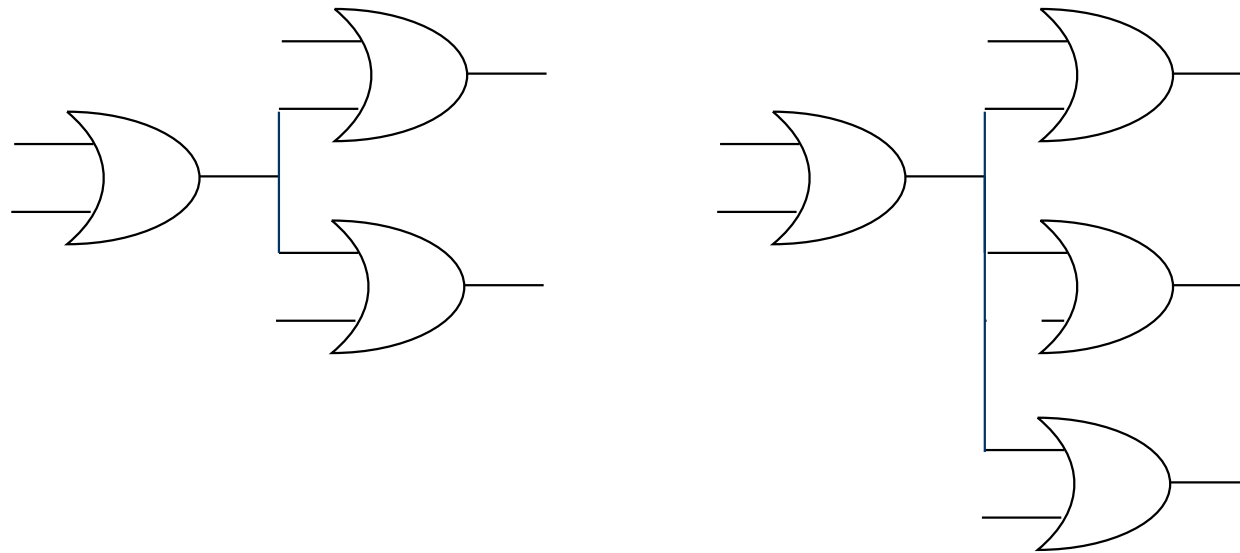
- ◆ For the proper functioning of a circuit some physical characteristics should be satisfied
- ◆ These are known as design rules
- ◆ Layouts have design rules like minimum width, minimum spacing etc
- ◆ For synthesis to be successful some electrical and physical characteristics should be met such as
 - Transition
 - Fanout
 - Capacitance

- ◆ The propagation delay of a gate is very much dependent on the time taken for data to switch from high to low or vice-versa
- ◆ The time taken for data to switch from high-low or vice-versa known as transition time depends mainly on
 - Load Capacitance
 - Wire length / characteristics - RC
 - Junction Capacitance of cell

Transition

- ◆ If the allowable transition time is restricted the design performance will increase significantly
- ◆ Every Gate and wire will have its own transition time
- ◆ By specifying appropriate constraint we can ensure that only those components are chosen that transit faster

Fanout



- ◆ In the above figure assuming that the same kind of ‘OR’ gates being used throughout
 - If input were provided at time 0 which of the 5 outputs would be faster?



- ◆ The delay of a system depends on the type of cells that are being used in the circuit
- ◆ Cells with high drive strength are required to efficiently drive high loads
- ◆ Cells with high drive strengths have more width and hence offer more capacitance

Limiting Fanout

- ◆ Layman explanation
 - *The number of gates a the output pin of cell can drive*
 - *The number of 'nand' gates that a cell can drive*
 - *The number of 'equivalent' gates that a cell can drive*
- ◆ Fanout is the measure of the ability of a logic gate output to drive a number of inputs of some other logic gates
- ◆ Every input pin of a gate has a '*fanout_load*' attribute specified in the library

Limiting Fanout



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- ◆ Every output pin of a gate has a '*max_fanout*' attribute specified
- ◆ The sum of all the fanout_loads of all the driven cells should not exceed the max_fanout attribute of the output pin of the driving cell
- ◆ It can be ensured that only specific cells are chosen which have a lower max_fanout attribute

Capacitance

- ◆ The transition as well as the fanout capacity are explicitly or implicitly dependent on the capacitance of the components
- ◆ By limiting the maximum capacitance in the circuit there can be made an attempt in improving the delay
- ◆ Capacitance, Transition and Fanout are the major Design rule constraints which need to be taken care of during synthesis
- ◆ They monitor the buffering of the design



Optimization Constraints

- ◆ The DRC exists on a design inherently
- ◆ When a designer does not specify DRC explicitly the values from the libraries are used while choosing the cells
- ◆ DRC constraints are imposed upon the design by requirements specified in the technology library
- ◆ Optimization constraints are the ones which convey the specifications of the design
 - Area
 - Power
 - Timing

Area Constraints



- ◆ In ASIC front end process ‘area’ refers to the sum of the cell areas + sum of wire areas
- ◆ Chip area depends on placement of cells and routing area
- ◆ Placement and routing are done down the flow hence can not be estimated up-front



- ◆ Every cell has an area attribute set in the library
- ◆ Design area is actually sum of all such cell areas and nett wire area (if provided in the library)
- ◆ The maximum as well as minimum limit on the area of a design can be set
- ◆ It has the least priority of all constraints

- ◆ Two kinds of Power needs to be looked into
 - Dynamic
 - Static / Leakage
- ◆ Dynamic power dissipation can be affected by the following factors
 - V_{DD}
 - Material Used
 - Switching
 - Short Circuit Current
 - Clock Gating
 - Operation Isolation



Power Optimization

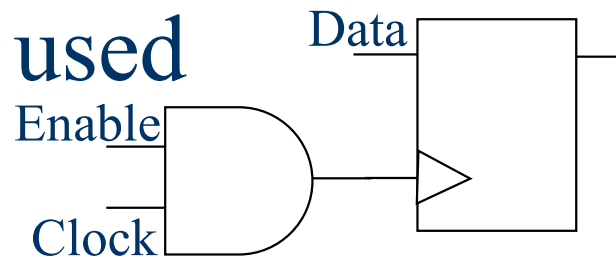
- ◆ Leakage Power can be optimized by
 - Multiple Threshold Voltages
 - Power Gating
- ◆ Power Depends on supply Voltage
- ◆ By reducing supply voltage power dissipation can be reduced
 - But decrease in supply voltage leads to increase in delay
 - Fine balance has to be created
 - Level shifters required
- ◆ Power depends on material used to fabricate the IC
- ◆ New technologies like Silicon-On-Insulator help in power optimization

Power Optimization

- ◆ Major component of power dissipation is due to switching
- ◆ The transitions of signal from high-low and vice versa causes capacitances to charge and discharge
- ◆ Power dissipation is huge during these cycles
- ◆ Depending on the rate of transition short circuit current also contributes to power dissipation
- ◆ This kind of power can be optimized by ensuring minimum switching
- ◆ Can be accounted for at the architecture level

Power Optimization

- ◆ During the operation of a circuit all registers are not active all the time
- ◆ Clock transition also contributes largely to power dissipation
- ◆ The clock to those flops which are not active can be switched off by clock gating
- ◆ By far the most dominant power optimization technique used



Leakage Power

- ◆ At VDSM technologies Leakage power constitutes a large percent of the total power dissipation
- ◆ Leakage power dissipation can be reduced by increasing threshold Voltage
- ◆ Increase in threshold voltage leads to increase in delay of the cell
 - Fine balance has to be created
- ◆ By ensuring that blocks which are not functionally required are switched off leakage current can be minimized
 - Known as power gating
 - Isolation cells , retention registers required



Constraints for Low Power

- ◆ Among all the low power methodologies discussed so far it can be seen that power optimization requires
 - usage of proper libraries
 - efficient architecture
 - appropriate materials
- ◆ It can be seen that at the synthesis level scope for power optimization is limited
- ◆ The major power optimizations done during synthesis are
 - Clock Gating
 - Multi V_{TH} Synthesis

Timing Constraints

- ◆ Synthesis can be considered as the process of choosing appropriate cells that meet the required specifications
- ◆ Unless otherwise specified the goal of synthesis is Timing Optimization
- ◆ Synthesis is timing driven and among all optimization constraints timing has highest priority
- ◆ All designs are sequential in nature and invariably have a clock
- ◆ Among all timing constraints the most important is that concerning the clock

- ◆ The most important aspect of the clock is its frequency
- ◆ Clock is that net which runs throughout the design and feeds all the flip-flops
- ◆ The load on the clock being huge a real clock will not be square wave in nature but will have a finite transition time
- ◆ Again due to the load as well as due to other reasons the time at which clock arrives at two flip-flops will not be the same – Skew
- ◆ Skew can be advantageous as well as disadvantageous depending on the kind of analysis being carried out
- ◆ The clock may either come early or late

Insertion Delay

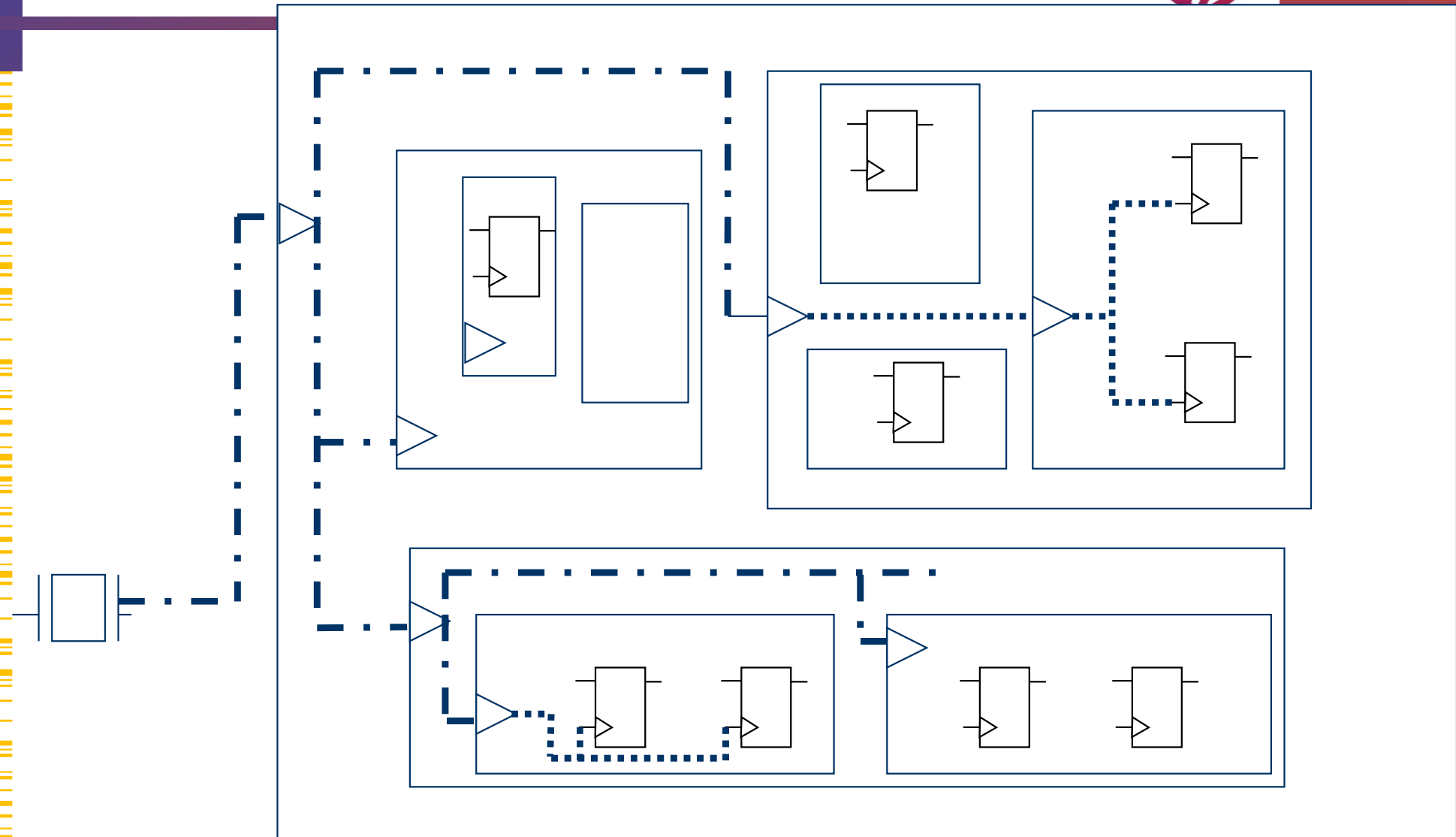


- ◆ Many modules together comprise a design
- ◆ Each of them may have their own clocks or share the same clock
- ◆ Designs will not have many oscillators / PLLs
- ◆ Same oscillator / PLL will be used to generate multiple clocks and then fed to the modules



- ◆ The difference in arrival of clock from the point of origin to the point of definition is known as clock insertion delay
- ◆ The difference (when external to the module being designed) is called as clock source insertion delay
- ◆ The difference (when internal to the module being designed) is known as clock network insertion delay

Insertion Delay



- . - . - Source Insertion Delay
- Network Insertion Delay

- ◆ The clock related constraints that should be provided are
 - Frequency
 - Duty Cycle
- ◆ The clock related information that can be provided are
 - Transition
 - Skew
 - Early
 - Late
 - Insertion Delay
 - Source
 - Network

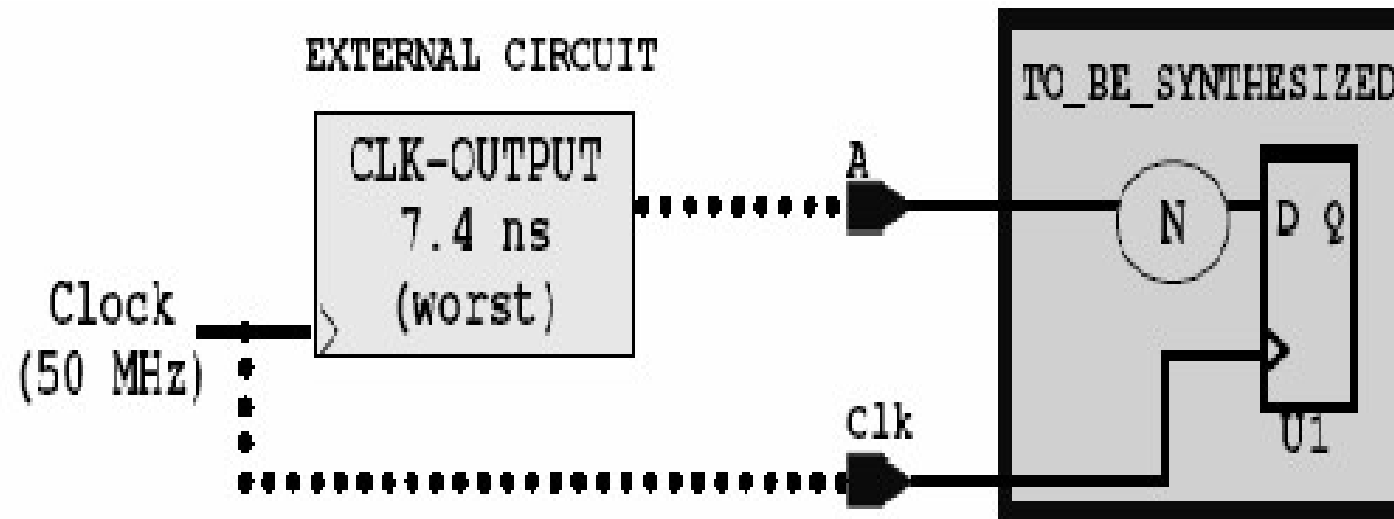
External Delay

- ◆ Complete IC need not be synthesized by same team or at the same time
- ◆ Modules designed one after the other
- ◆ A module might work well in isolation – not sufficient
- ◆ Should work well even after top level integration
- ◆ External delay information needs to be provided while synthesizing the design
- ◆ The external delay could be both at the input as well as the output of the circuit being designed
- ◆ Both Input external delay as well as output external delay information need to be provided



Input External Delay

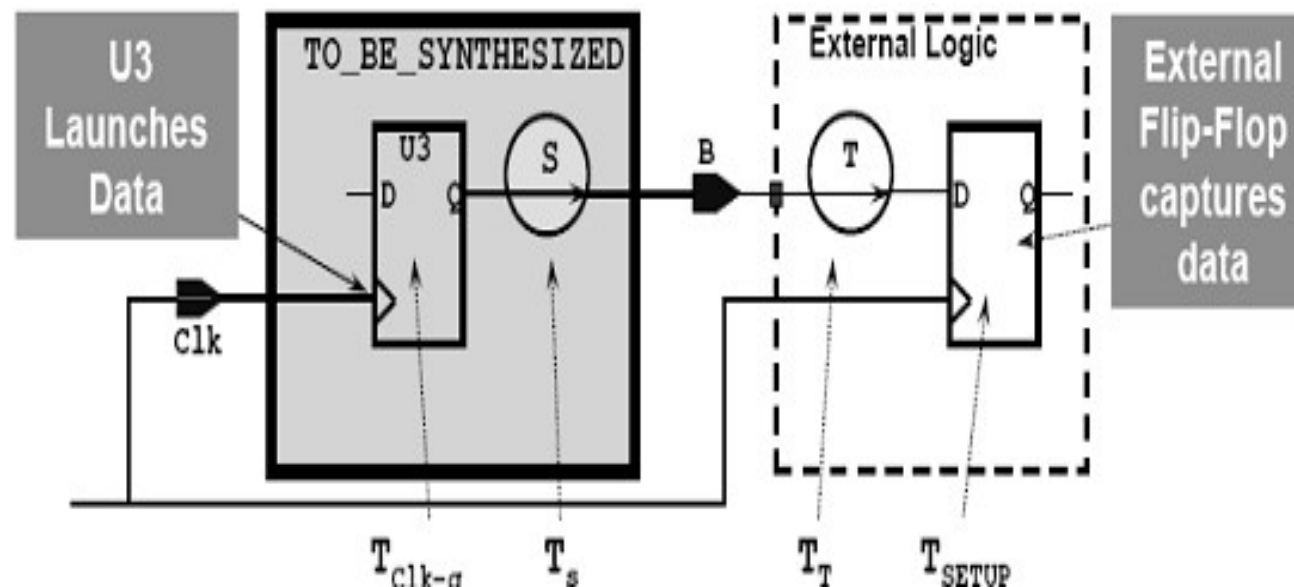
- ♦ A input external delay information helps in optimizing the logic between the input and the first flip-flop
- ♦ Typically affects input \rightarrow reg paths



- ♦ In design above an optimization will be attempted on logic 'N' so that it can accommodate the external delay of 7.4 ns

Output External delay

- ◆ An output external delay information helps in optimizing the logic between the last flip-flop / register bank and the output
- ◆ May affect reg -> Out paths

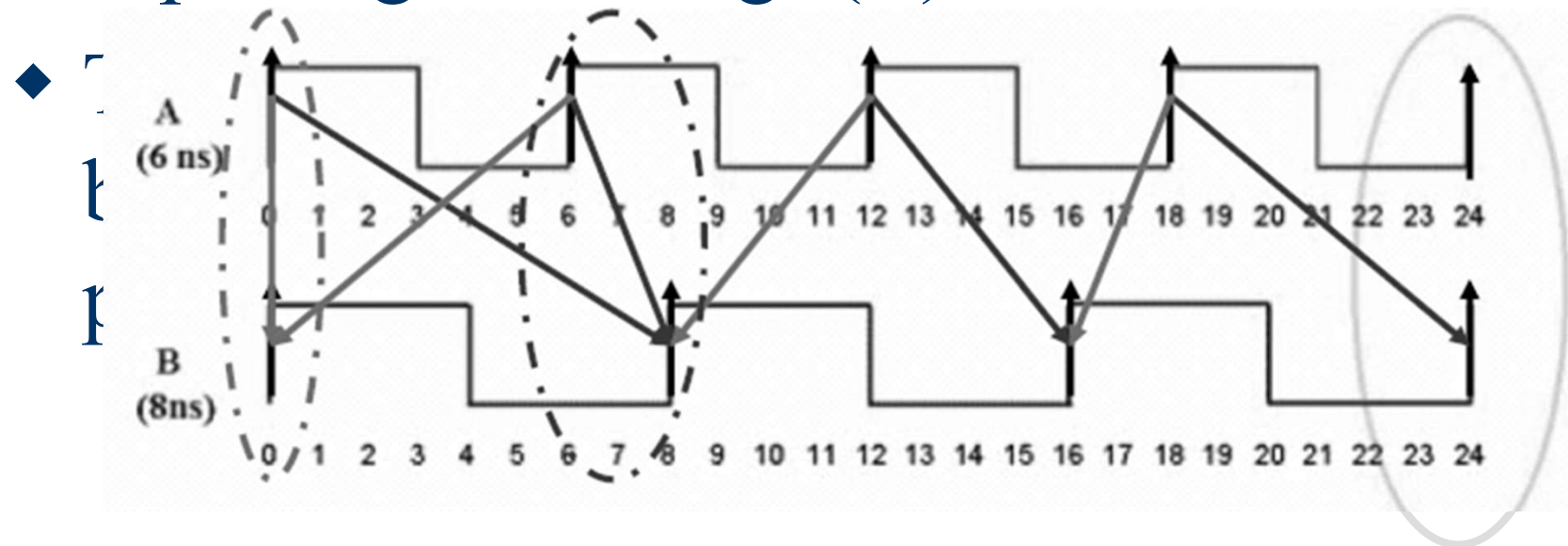


- ◆ In design above an optimization will be attempted on logic 'S' so that it can accommodate the external delay provided by the logic 'T'



Multiple Clock Analysis

- ◆ Determine the least common multiple (LCM) of the 2 clock periods first
- ◆ The setup relationship is the closest distance between the launching clock edge (A) and the capturing clock edge (B)



Timing Exceptions

- ◆ In any given design the data once launched at the start point is expected at the end point within one clock cycle
- ◆ All paths are considered as single cycle paths
- ◆ There may be times where it may be required for data to arrive much earlier than the normal single clock cycle
- ◆ Any path which has a more restrictive timing constraint than one clock cycle is known to be having Timing exception



Point - Point Exceptions

- ◆ When the exception is between Input \rightarrow reg known as point – clock exception
- ◆ When the exception is between reg \rightarrow out path known as clock – point exception
- ◆ When the exception is between input \rightarrow output known as point – point exception

◆ Environment

- `set_min_library tcb013ghplvtwc.db –min_version tcb013ghplvtbc.db`
- `set_operating_conditions WCCOM`
- `set_wire_load_model FORQA`
- `set_wire_load_mode TOP`

◆ DRC

- `set_max_transition 0.01 [current_design]`
- `set_max_fanout 5 [current_design]`
- `set_max_capacitance 0.05 [current_design]`

Optimization Constraints



- ◆ Area
 - `set_max_area 3000`
 - `set_min_area 0`
- ◆ Power
 - `set_max_dynamic_power 20 mw`
 - `set_max_leakage_power 10 uw`
- ◆ Timing
 - `create_clock –period 4 –waveform {1 0} –name master_clock`
 - `set_clock_transition 0.04 master_clock`
 - `set_clock_uncertainty –setup 0.4 master_clock`
 - `set_clock_uncertainty –hold 0.2 master_clock`
 - `set clock_latency –network 0.35 master clock`

Hierarchy of constraints



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- ◆ The following are the hierarchy of constraints
 - Min Capacitance
 - Max Transition
 - Max Fanout
 - Max Capacitance
 - Max Delay
 - Min Delay
 - Max Power
 - Max Area

◆ Exceptions

- `set_max_delay 3 –from [all_inputs] –to [all_outputs]`
 - applies to all the logic which lies in the path from input to output
 - If there is no path from input to output constraint is ignored
- `set_max_delay 2 –from [all_inputs]`
 - applies to all paths which start from the input
 - Can be input to output path as well as input -> reg path
- `set_max_delay 1.8 –to [all_outputs]`
 - applies to all paths ending at the output
 - can be input to output paths as well as reg -> output paths

◆ External Delay Information

- `set_input_delay 1 [all_inputs]`
- `set_output_delay 1 [all_outputs] –clock master_clock`

Constraints

